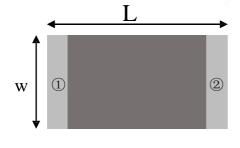
Features

- 1. Surface mounted devices with a small dimension of $1.6 \times 0.8 \times 0.8$ mm meet future miniaturization
- 2. Embedded and LTCC (low temperature co-fired ceramic) technology is able to integrate with system design as well as beatifying the housing of final product.
- 3. High stability and low tolerance.

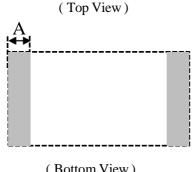
Applications

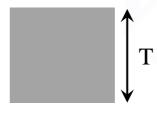
- 1. Bluetooth
- 2. Wireless LAN
- 3. ISM band 2.4GHz wireless applications

Dimensions (Unit: mm)



Number	Terminal Name
1	INPUT
2	NC



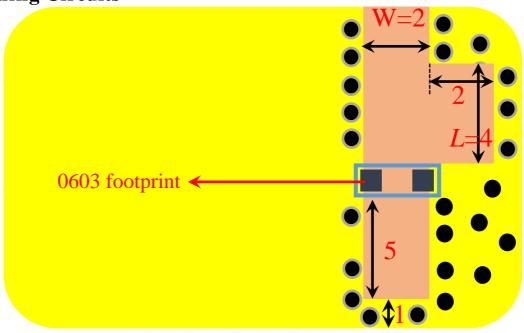


(Bottom View)

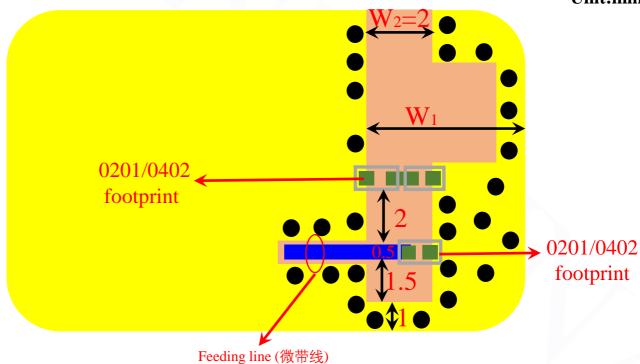
(Side View)

Symbols	L	W	Т	A	
Dimensions	Dimensions 1.60 ± 0.20		0.80 ± 0.20	0.30 ± 0.10	

Matching Circuits



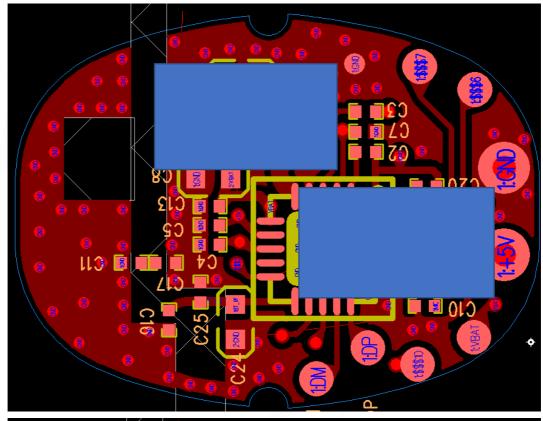
Unit:mm

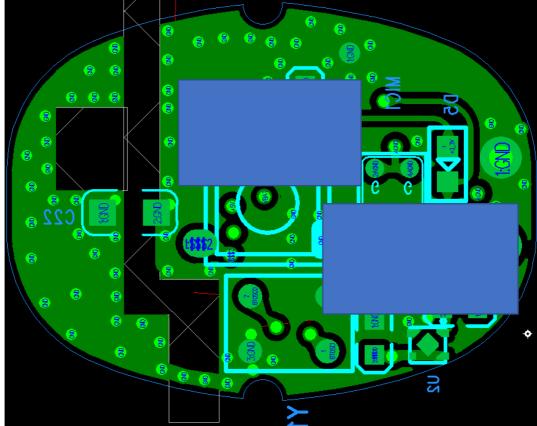


设计指导:

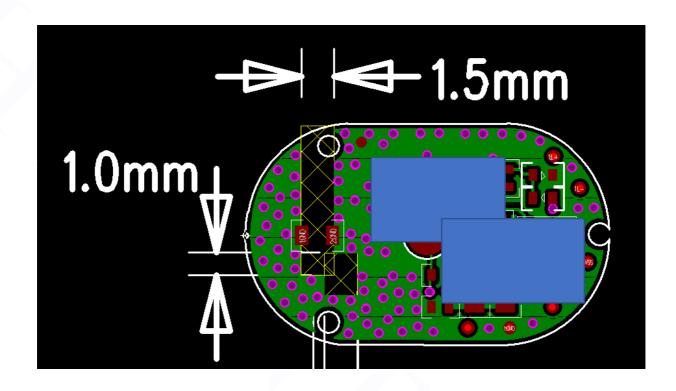
- 1、原则上,净空区左侧边缘距离板边的间距W1应该尽量大,且注意与底部电池的间距。
- 2、主净空区的宽度W2最优为1.5mm~2.5mm。
- 3、凹槽的长度L的长度为2mm~5mm。
- 4、0603天线和0603天线底部的两颗物料可以上下互换位置。

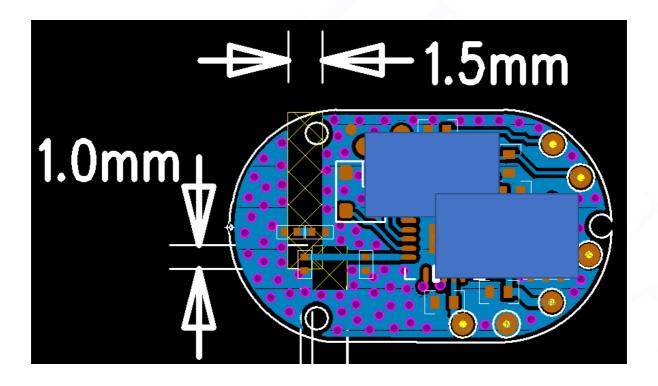
Application example-1





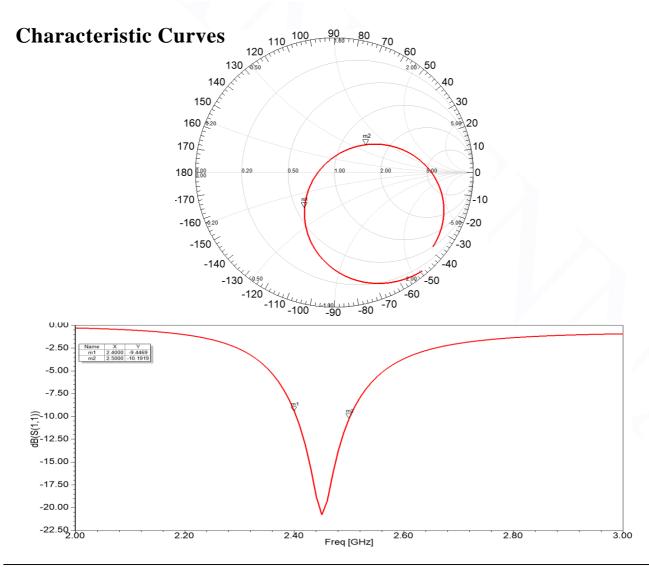
Application example-2

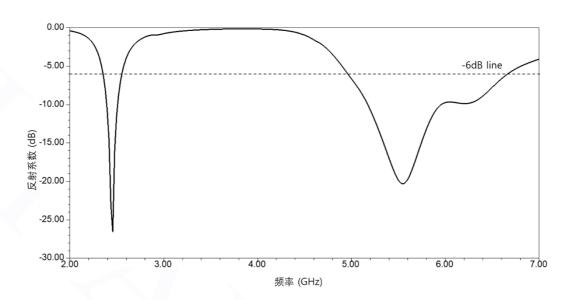




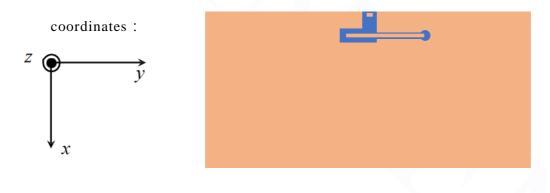
Electrical Characteristics

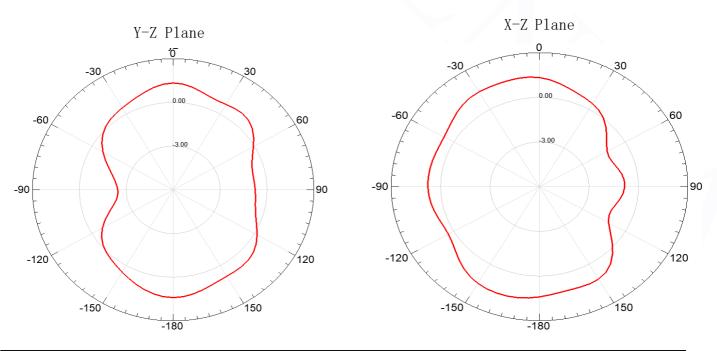
	Feature	Specification		
1	Central frequency	2.45GHz		
2	Bandwidth	>100MHz		
3	Peak gain	3dBi		
4	VSWR	<2		
5	Polarization	Linear		
6	Azimuth beamwidth	Omnidirectional		
7	Impedance	50Ω		

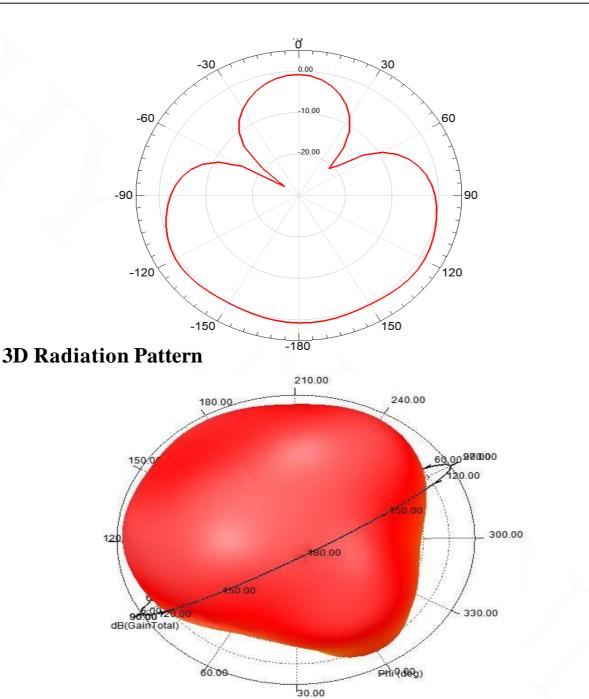




Radiation Pattern







Frequency	2450MHz
Avg. gain	-0.85
Peak gain	3.0
Efficiency	82%



Dependability Test

Test Temperature $25^{\circ}\text{C} \pm 3^{\circ}\text{C}$ Operating Temperature $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$ Temperature $5\sim 40^{\circ}\text{C}$ Relative Humidity $20\sim 70\%$

Moisture Proof

Temperature: 40±2°C Humidity: 90~95%RH

Duration: 500h

Recovery conditions: Room temperature Recovery Time: 24h (Class1) or 48h (Class2)

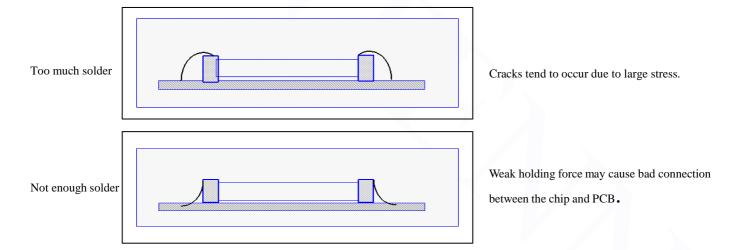
Solderability

At least 95% of the terminal electrode is covered by new solder.

Preheating conditions:80 to 120°C; 10~30s.

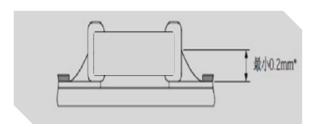
Solder Temperature: 235 ± 5°C Duration: 2 ± 0.5s, Solder Temperature: 245 ± 5°C Duration: 2 ± 0.5s

Optimum Solder Amount for Reflow Soldering

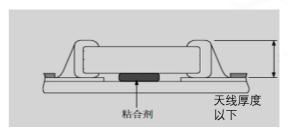


Recommended Soldering Amounts

The optimal solder fillet amounts for re-flow soldering



The optimal solder fillet amounts for wave soldering



Temperature Cycle Test

 10 ± 1 S Applied Force: 5N Duration: 10 ± 1 S Preheating conditions: up-category temperature, 1h

Recovery time: 24±1h Initial Measurement

Cycling Times: 5 times, 1 cycle, 4 steps:

阶段	温度(℃)	时间(分钟)
第1步	下限温度(NPO/X7R/X7S/X6S/X5R:-55)	30
第2步	常温 (+20)	2~3
第3步	上限温度(NPO/X7R/X78:+125 YSV/ZSU/X5R:+85 X68:+105)	30
第4步	常温 (+20)	2~3

Resistance to Soldering Heat

Preheating 80 to 120°C; 10~30s.SolderTemperature: 235±5°C; Duration: 2±0.5s; SolderTemperature: 245±5°C

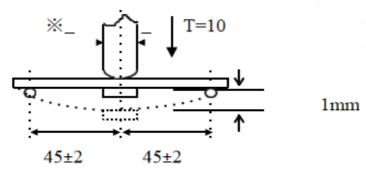
Duration: 2±0.5s; Preheating 100 to 200°C; 10±2min. Solder Temperature: 265±5°C; Duration: 10±1s

Clean the capacitor with solvent and examine it with a 10X(min.) microscope.

Recovery Time: 24±2h

Recovery condition: Room temperature

Resistance to Flexure of Substrate

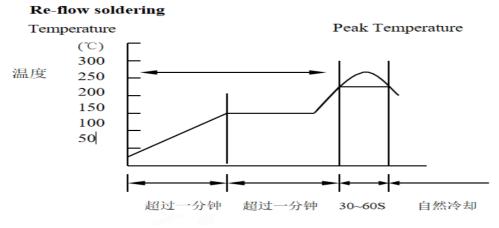


Test Board: Al₂O₃ or PCB Warp: 1mm Speed: 0.5mm/sec.

Unit: mm

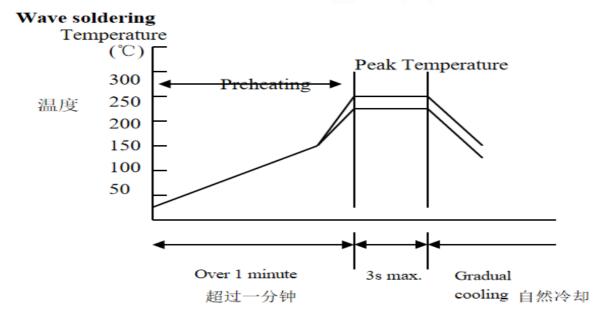
The measurement should be made with the board in the bending position.

The temperature profile for soldering



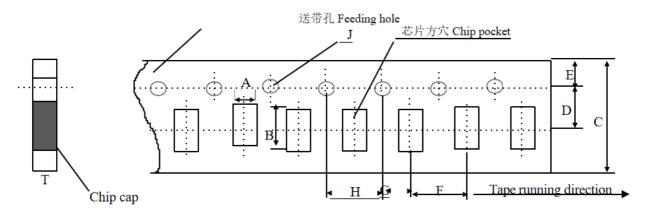
	Pb-Sn 焊接	无铅焊接	
	Pb-Sn soldering	Lead-free soldering	
尖峰温度 Peak temperature	230℃~250℃	240℃~260℃	

While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as: $T \le 150$ °C.



	Pb-Sn 焊接	无铅焊接		
	Pb-Sn soldering	Lead-free soldering		
尖峰温度	230℃~260℃	240℃~270℃		
Peak temperature	2300 2000	2100 2700		

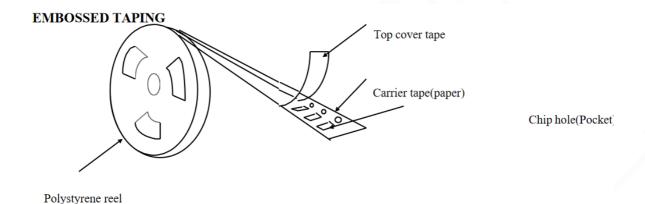
Dimensions of paper taping



Unit: mm

代号Code 纸带规格 papersize	A	В	С	D*	E	F	G*	Н	J	Т
+	1.10	1.90	8.00	3.50	1.75	4.00	2.00	4.00	1.50	1.10
尺寸 	±0.10	±0.10	±0.10	±0.05	±0.10	±0.10	±0.10	±0.10	-0/+0.10	Max

Reel (4000 pcs/Reel)



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition). Temperature:5~40°C /Relative Humidity:20~70%